

MCDN 1,5/13-G1-3,5 RNP26THR - PCB header



1953635

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PCB headers, nominal cross section: 1.5 mm², color: black, nominal current: 8 A, rated voltage (III/2): 160 V, contact surface: Sn, contact connection type: Pin, number of potentials: 26, number of rows: 2, number of positions: 13, number of connections: 26, product range: MCDN 1,5/...-G1-RN-THR, pitch: 3.5 mm, mounting: THR soldering / wave soldering, pin layout: Linear pinning, solder pin [P]: 2.6 mm, number of solder pins per potential: 1, plug-in system: COMBICON FMC 1,5 - MCDN 1,5, Pin connector pattern alignment: Standard, locking: Snap-in locking, mounting method: Engagement nose, type of packaging: packed in cardboard, Article with engagement nose. The pin length is 2.6 mm. User information and design recommendations on Through Hole Reflow Technology can be found at: "Downloads"

Your advantages

- Designed for integration into the SMT soldering process
- Intuitive locking mechanism prevents accidental disconnection
- Conductor connection on several levels enables higher contact density

Commercial data

Item number	1953635
Packing unit	40 pc
Minimum order quantity	40 pc
Sales key	AABTGA
Product key	AABTGA
Catalog page	Page 219 (C-1-2013)
GTIN	4017918919542
Weight per piece (including packing)	10.75 g
Weight per piece (excluding packing)	9.506 g
Customs tariff number	85366990
Country of origin	DE

Technical data

Product properties

Product type	PCB headers
Product family	MCDN 1,5/...G1-RN-THR
Product line	COMBICON Connectors S
Type	Component suitable for through hole reflow
Number of positions	13
Pitch	3.5 mm
Number of connections	26
Number of rows	2
Number of potentials	26
Mounting flange	Engagement nose
Pin layout	Linear pinning
Solder pins per potential	1

Electrical properties

Properties

Nominal current I_N	8 A
Nominal voltage U_N	160 V
Contact resistance	2.1 mΩ
Rated voltage (III/3)	160 V
Rated surge voltage (III/3)	2.5 kV
Rated voltage (III/2)	160 V
Rated surge voltage (III/2)	2.5 kV
Rated voltage (II/2)	250 V
Rated surge voltage (II/2)	2.5 kV

Mounting

Mounting type	THR soldering / wave soldering
Pin layout	Linear pinning

Processing notes

Process	Reflow/wave soldering
Moisture Sensitive Level	MSL 1
Classification temperature T_c	260 °C
Solder cycles in the reflow	3

Material specifications

Material data - contact

Note	WEEE/RoHS-compliant, free of whiskers according to IEC 60068-2-82/JEDEC JESD 201
Contact material	Cu alloy

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Surface characteristics	Tin-plated
Metal surface contact area (top layer)	Tin (3 - 5 µm Sn)
Metal surface contact area (middle layer)	Nickel (1 - 3 µm Ni)
Metal surface soldering area (top layer)	Tin (3 - 5 µm Sn)
Metal surface soldering area (middle layer)	Nickel (1 - 3 µm Ni)

Material data - housing

Color (Housing)	black (9005)
Insulating material	LCP
Insulating material group	IIIa
CTI according to IEC 60112	175
Flammability rating according to UL 94	V0

Notes

Details for soldering processes	Processing using reflow processes in compliance with IEC 60068-2-58 or DIN EN 61760-1 (latest version) Moisture Sensitive Level (MSL) = 1 according to IPC/JEDEC J-STD-020-C
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Dimensions

Dimensional drawing	
Pitch	3.5 mm
Width [w]	49.2 mm
Height [h]	17.8 mm
Length [l]	13.3 mm
Installed height	15.2 mm
Solder pin length [P]	2.6 mm
Pin dimensions	0.8 x 0.8 mm

PCB design

Pin spacing	3.50 mm
Hole diameter	1.4 mm

Mechanical tests

Visual inspection

Specification	IEC 60512-1-1:2002-02
Result	Test passed

Dimension check

Specification	IEC 60512-1-2:2002-02
Result	Test passed

Resistance of inscriptions

Specification	IEC 60068-2-70:1995-12
Result	Test passed

Polarization and coding

Specification	IEC 60512-13-5:2006-02
Result	Test passed

Contact holder in insert

Specification	IEC 60512-15-1:2008-05
Contact holder in insert Requirements >20 N	Test passed

Insertion and withdrawal forces

Result	Test passed
No. of cycles	25
Insertion strength per pos. approx.	8 N
Withdraw strength per pos. approx.	6 N

Electrical tests

Thermal test | Test group C

Specification	IEC 60512-5-1:2002-02
Tested number of positions	20

Insulation resistance

Specification	IEC 60512-3-1:2002-02
Insulation resistance, neighboring positions	> 5 MΩ

Air clearances and creepage distances |

Specification	IEC 60664-1:2007-04
Insulating material group	IIIa
Comparative tracking index (IEC 60112)	CTI 175
Rated insulation voltage (III/3)	160 V
Rated surge voltage (III/3)	2.5 kV
minimum clearance value - non-homogenous field (III/3)	1.5 mm
minimum creepage distance (III/3)	2.5 mm
Rated insulation voltage (III/2)	160 V
Rated surge voltage (III/2)	2.5 kV
minimum clearance value - non-homogenous field (III/2)	1.5 mm
minimum creepage distance (III/2)	1.6 mm
Rated insulation voltage (II/2)	250 V
Rated surge voltage (II/2)	2.5 kV
minimum clearance value - non-homogenous field (II/2)	1.5 mm
minimum creepage distance (II/2)	2.5 mm

Environmental and real-life conditions

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Vibration test

Specification	IEC 60068-2-6:2007-12
Frequency	10 - 150 - 10 Hz
Sweep speed	1 octave/min
Amplitude	0.35 mm (10 Hz ... 60.1 Hz)
Acceleration	5g (60.1 Hz ... 150 Hz)
Test duration per axis	2.5 h
Test directions	X-, Y- and Z-axis

Durability test

Specification	IEC 60512-9-1:2010-03
Impulse withstand voltage at sea level	2.95 kV
Contact resistance R_1	2.1 mΩ
Contact resistance R_2	2.4 mΩ
Insertion/withdrawal cycles	25
Insulation resistance, neighboring positions	> 5 MΩ

Climatic test

Specification	ISO 6988:1985-02
Corrosive stress	0.2 dm ³ SO ₂ on 300 dm ³ /40 °C/1 cycle
Thermal stress	100 °C/168 h
Power-frequency withstand voltage	1.39 kV

Ambient conditions

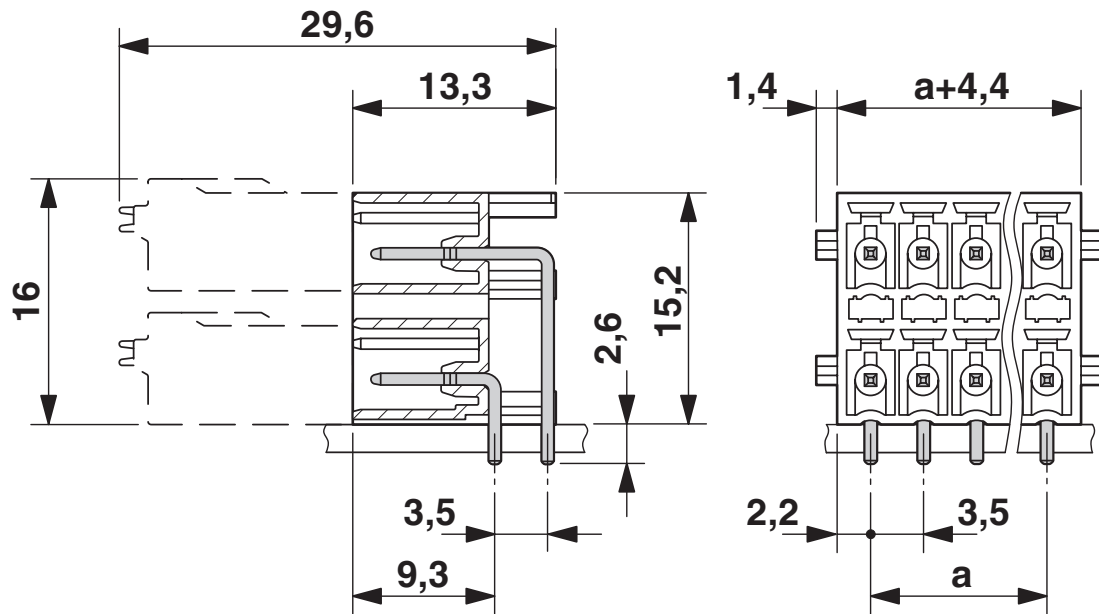
Ambient temperature (operation)	-40 °C ... 100 °C (dependent on the derating curve)
Ambient temperature (storage/transport)	-40 °C ... 70 °C
Relative humidity (storage/transport)	30 % ... 70 %
Ambient temperature (assembly)	-5 °C ... 100 °C

Packaging specifications

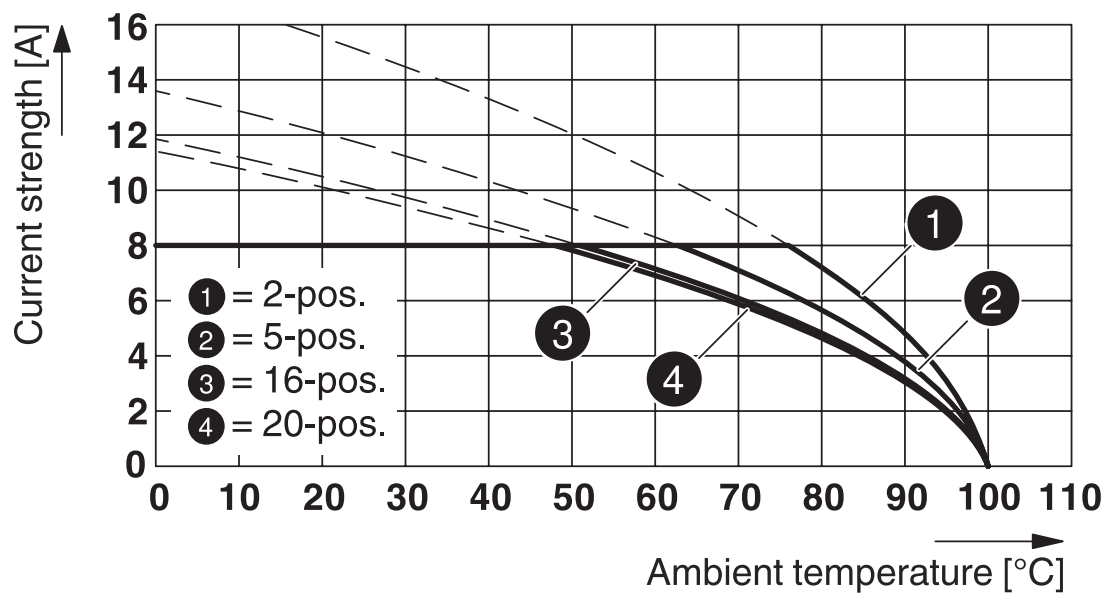
Type of packaging	packed in cardboard
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Drawings

Dimensional drawing



Diagram



Type: FMC 1,5/...-ST-3,5-RF with MCDN 1,5/...-G1-3,5 RNP..THR

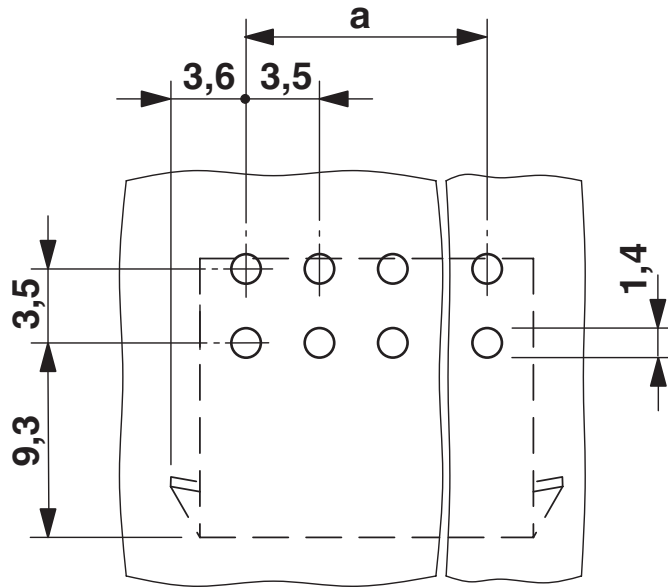
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Drilling plan/solder pad geometry


$$^*) \leq 8\text{-pos.} = 1.3 / > 8\text{-pos.} = 1.4$$

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Approvals

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 cULus Recognized Approval ID: E60425-20110128				
	Nominal voltage U_N	Nominal current I_N	Cross section AWG	Cross section mm^2
Use group B	150 V	8 A	-	-
Use group D	150 V	8 A	-	-

 VDE approval of drawings Approval ID: 40011723				
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Classifications

ECLASS

ECLASS-13.0	27460201
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ETIM

ETIM 9.0	EC002637
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UNSPSC

UNSPSC 21.0	39121400
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Environmental product compliance

EU RoHS

Fulfills EU RoHS substance requirements	Yes, No exemptions
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China RoHS

Environment friendly use period (EFUP)	EFUP-E
	No hazardous substances above the limits

EU REACH SVHC

REACH candidate substance (CAS No.)	No substance above 0.1 wt%
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EF3.0 Climate Change

CO2e kg	0.117 kg CO2e
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